

# New Non-Pyrophoric Al Precursor for the ALD of Al<sub>2</sub>O<sub>3</sub>: Influence of Purity Grade on Silicon Surface Passivation

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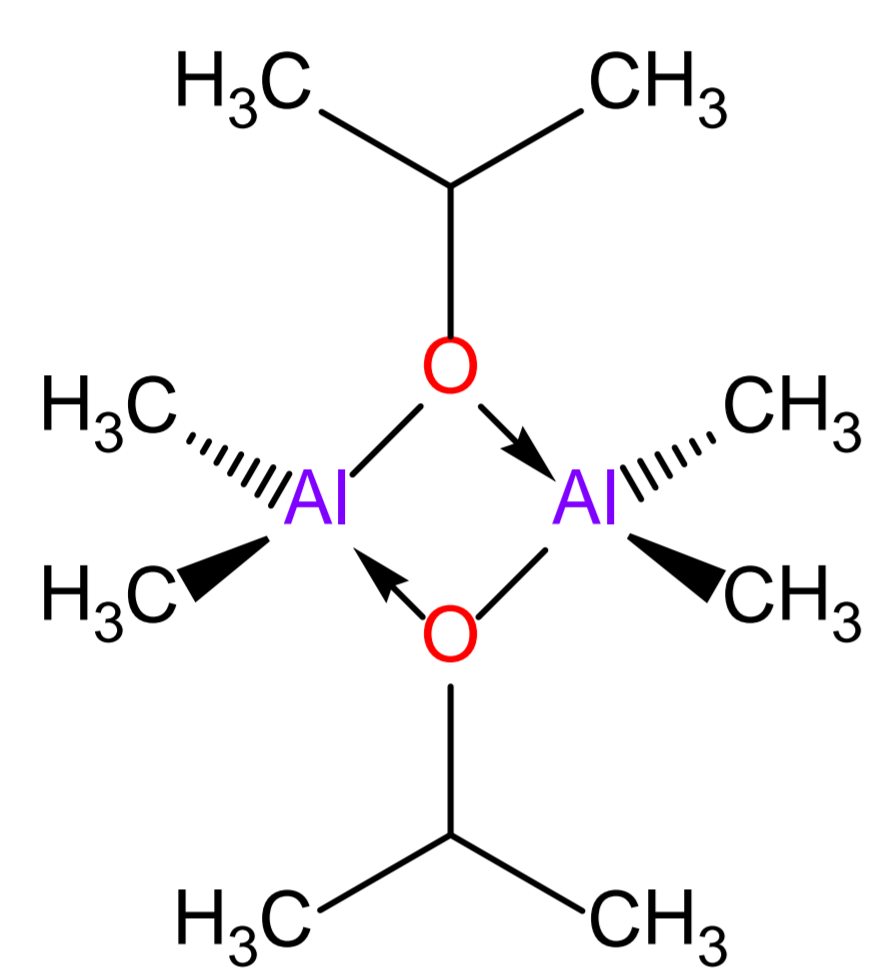
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## 1. Introduction

Al<sub>2</sub>O<sub>3</sub> deposited by atomic layer deposition (ALD) is known to provide excellent surface passivation of crystalline silicon (*c*-Si) solar cells [1,2]. However, metal impurities in passivation layers can significantly affect the cell's efficiency [3]. A potential source of these impurities is the precursor gas used to deposit the layers. Therefore, we have investigated the effect of precursor purity on the surface passivation of Al<sub>2</sub>O<sub>3</sub>. The most commonly-used Al precursor is trimethylaluminium (TMA), which is a pyrophoric liquid. We recently reported the use of dimethylaluminium isopropoxide (DMAI) as a safer, non-pyrophoric alternative [4], where it was shown to give comparable results to TMA with respect to effective lifetimes in *c*-Si. We present here the use of DMAI spiked with Fe to test the significance of precursor purity.

## 2. Aluminium Precursor



Dimethylaluminium isopropoxide (DMAI)

|                         |                   |
|-------------------------|-------------------|
| Physical State (R.T.P.) | Liquid            |
| Melting Point           | < R.T.            |
| Boiling Point           | 186 °C            |
| Vapour Pressure         | 9 Torr at 66.5 °C |
| Decomposition Temp.     | ~370 °C           |
| Pyrophoric              | No                |

**Purity Levels**

- Unspiked (99.999%)
- 5 ppm Fe
- 500 ppm Fe

## 3. Experimental Details

### ALD

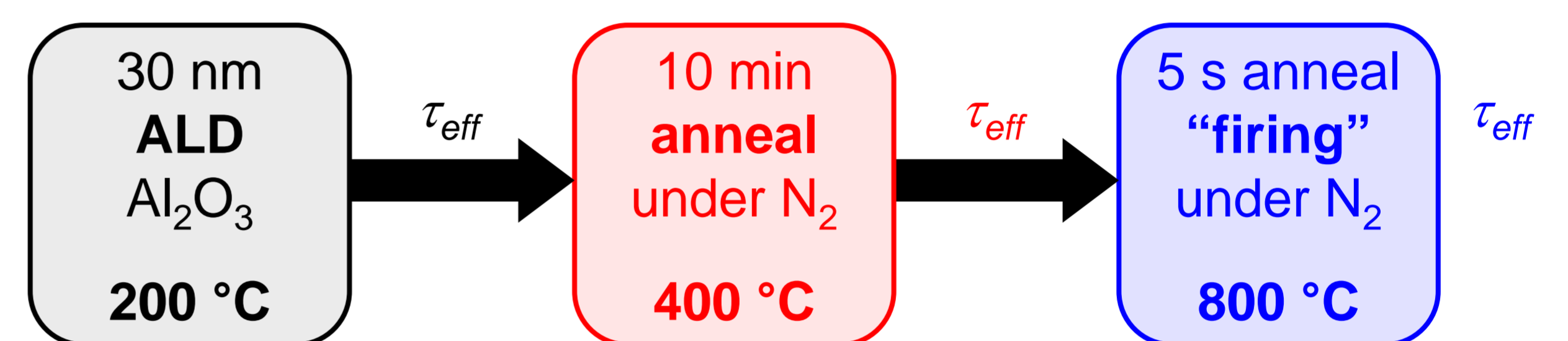
- Oxford Instruments OpAL™ reactor
- Plasma and thermal ALD

### Effective Lifetime Measurements

- Sinton WCT-100 Photoconductance tool

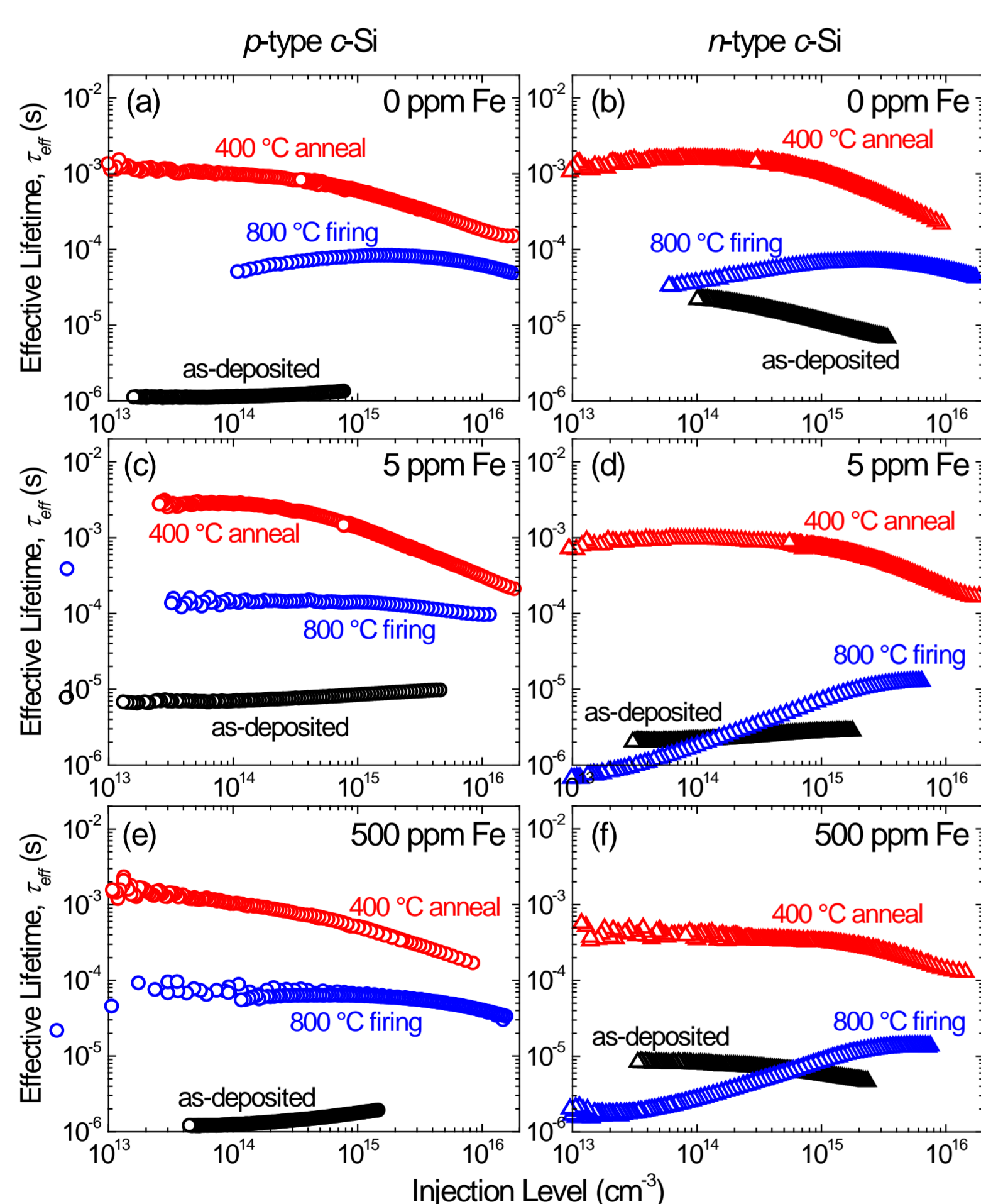
### Substrates

- Double-side-polished floatzone Si
- *n*-type (~3.5 Ω.cm)
- *p*-type (~2.0 Ω.cm)
- HF-dip before depositions



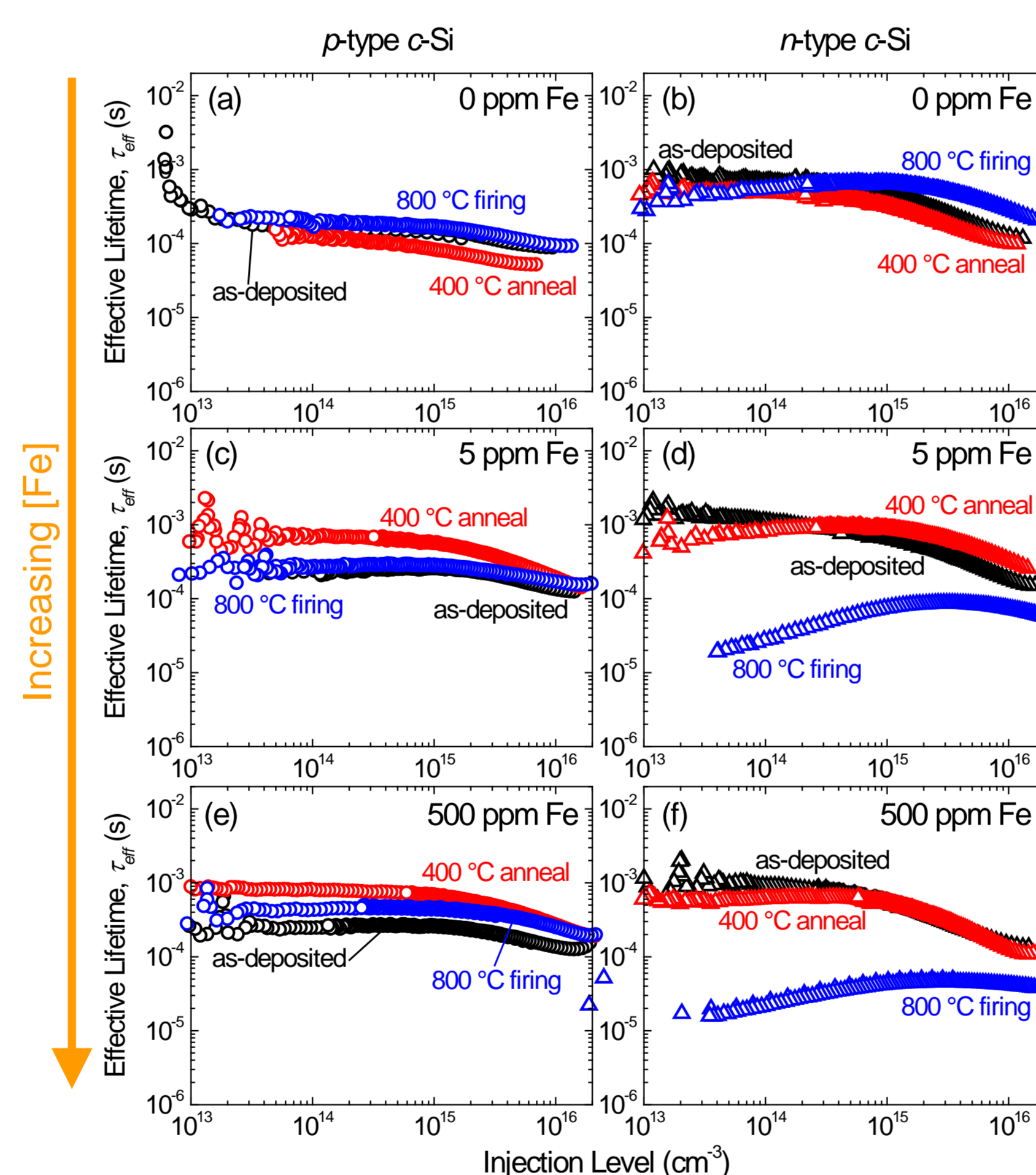
## 4. Effective Lifetime ( $\tau_{eff}$ ) Measurements

### Plasma-Enhanced ALD



**Fig. 1.** Variation of effective lifetimes with Fe content for plasma-enhanced ALD films.

### Thermal ALD

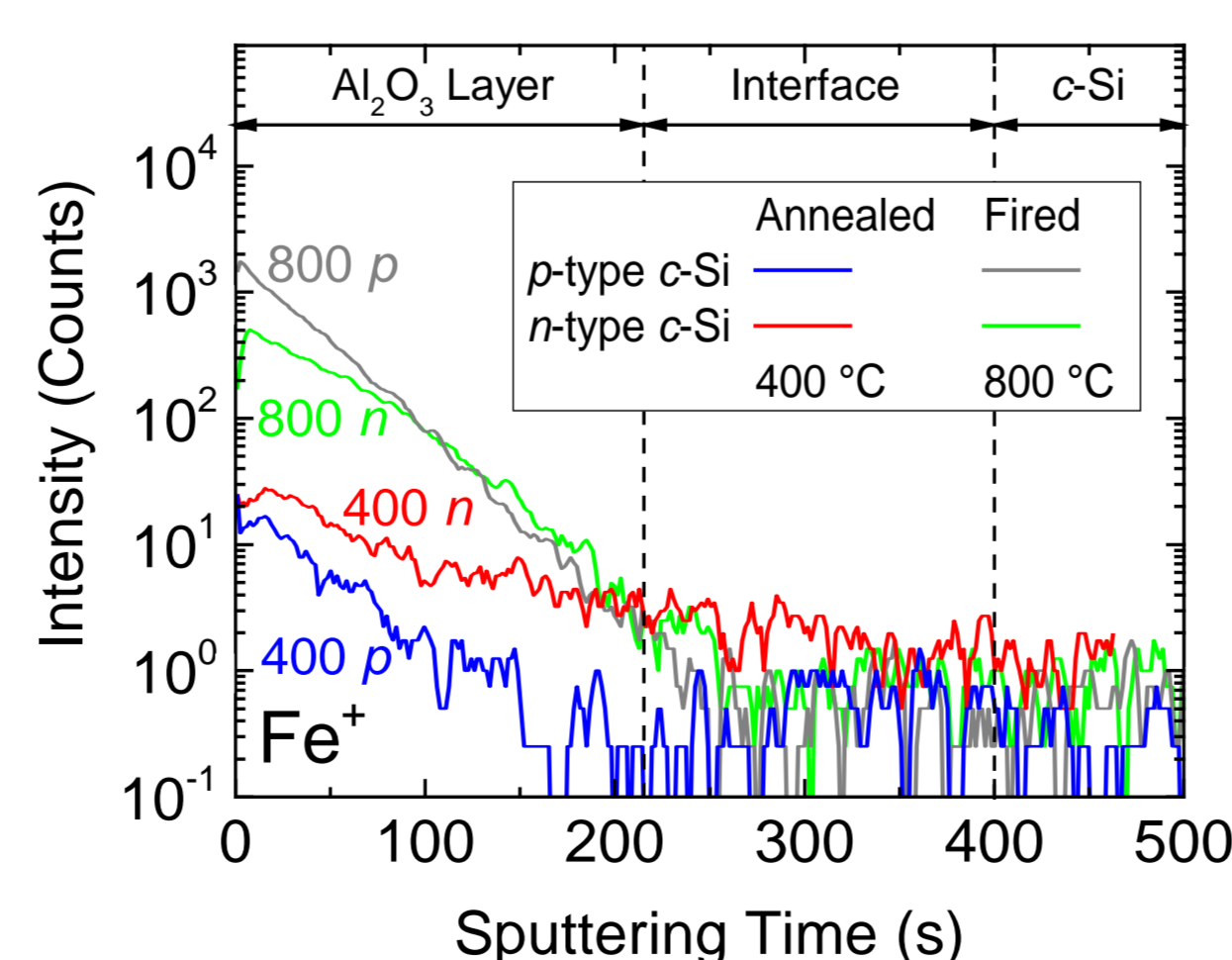


**Fig. 2.** Variation of effective lifetimes with Fe content for thermal ALD films.

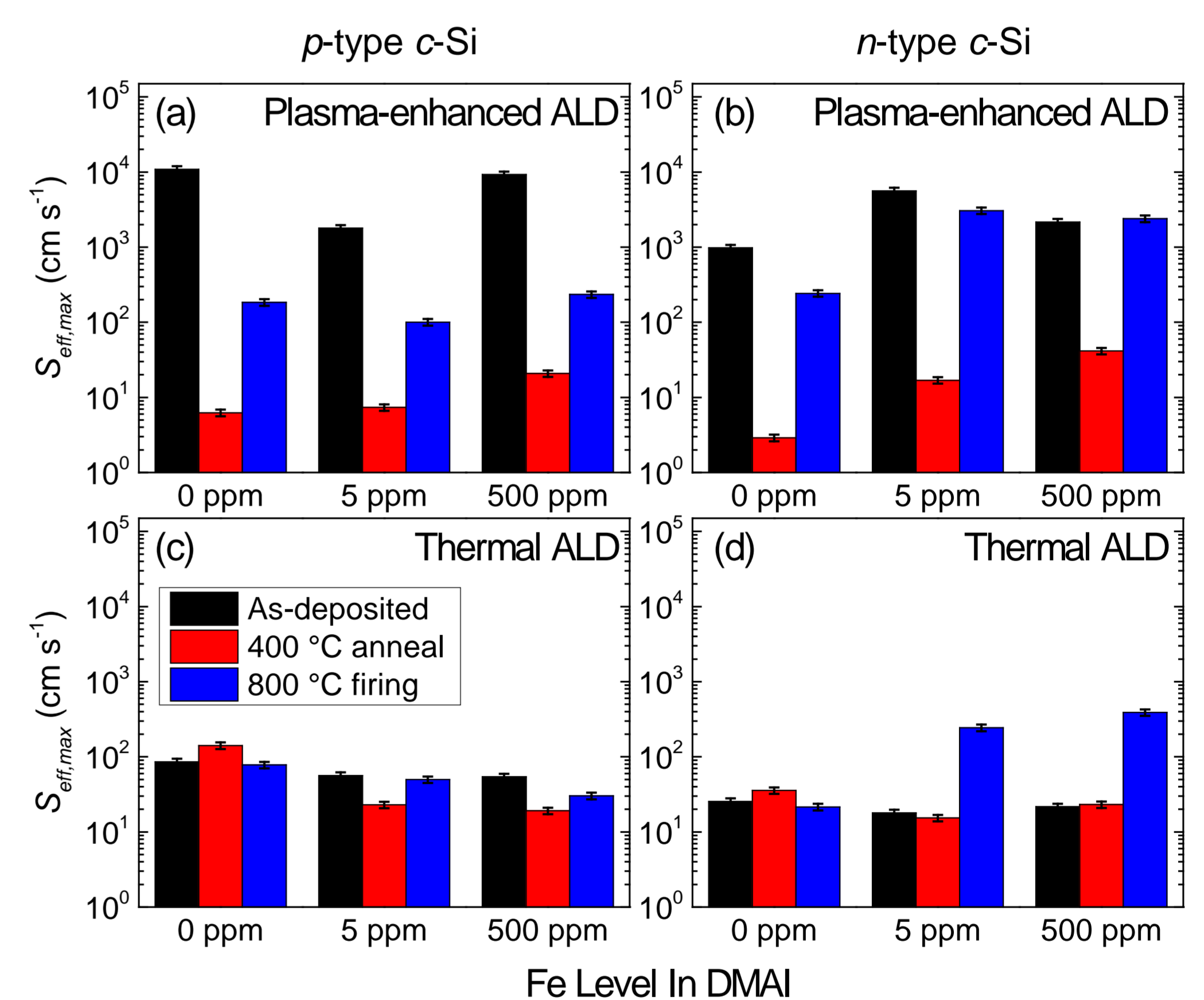
## 6. ToF-SIMS Measurements

- Fe mainly observed in the Al<sub>2</sub>O<sub>3</sub> layer, nearer the surface.
- Fe in the layer increases during firing.
- There is possibly some diffusion of Fe to the interface.

**Fig. 4 (right).** ToF-SIMS Fe<sup>+</sup> ion profile for annealed and fired Al<sub>2</sub>O<sub>3</sub> films on *n*- and *p*-type *c*-Si.



## 5. Recombination Velocities ( $S_{eff,max}$ )



**Fig. 3.** Surface recombination velocities for *n*- and *p*-type *c*-Si showing the effect of Fe content in the DMAI precursor.

## 7. Conclusions

- Samples prepared using plasma-enhanced ALD were more affected by the presence of Fe than thermal ALD.
- The plasma-enhanced ALD samples were more affected by firing than the thermal ALD samples.
- The highest lifetimes were obtained by annealing (not firing) the plasma-enhanced ALD samples.
- *n*-type *c*-Si was more affected by the Fe than *p*-type.
- For *n*-type substrates, the presence of Fe reduces the effective lifetimes after firing.
- Up to 5 ppm Fe in the Al precursor can be considered non-detrimental to the effective lifetimes on *p*-type *c*-Si.